



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2822  
#14/ Response  
A7nd  
6/3/03

In re the Application of:

Coyle, et al.

Docket No.: TI-31794

Serial No.: 09/992,387

Examiner: Lewis, Monica

Filed: 11/16/01

Art Unit: 2822

For: Flip-Chip on Film Assembly for Ball Grid Array Packages

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450 on

May 27, 2003.

  
Elizabeth Austin

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated 02/26/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

RECEIVED  
JUN - 2 2003  
TECHNOLOGY CENTER 2800